

ABSTRACT OF THE DISCLOSURE

An electronic circuit device, includes: internal terminals; a board on which wirings to the internal terminals are formed; an electronic component that is mounted on the board and is connected with the internal terminals;
5 and an encapsulation resin with which the electronic component and the internal terminals are encapsulated. A part of the wiring forms a ring-shaped portion, and the ring-shaped portion has a plurality of gaps by which the ring-shaped portion is divided into a plurality of discontinuous ring-constituting sections. The plurality of ring-constituting sections are
10 connected to the respective internal terminals, and a coating region of the encapsulation resin is surrounded with the ring-shaped portion. The applied area of the encapsulation resin can be controlled to be constant without using a special element for controlling the flow of the encapsulation resin.